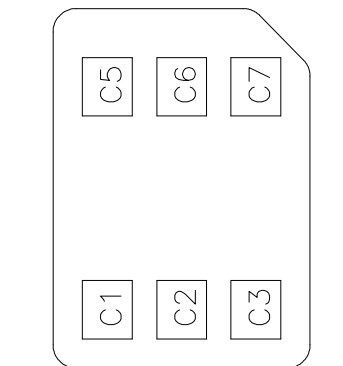
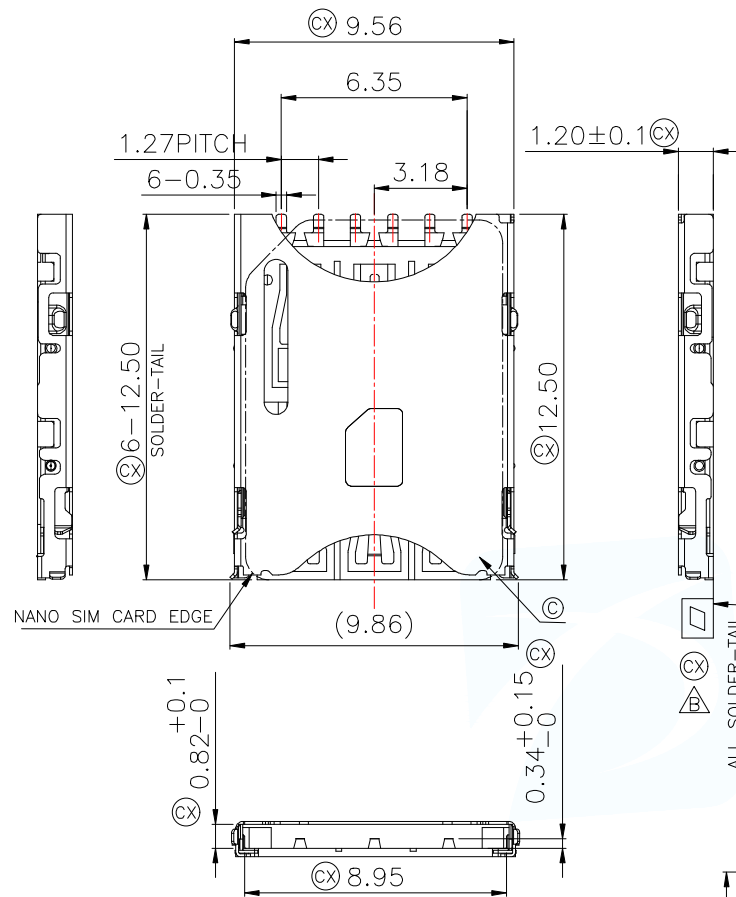
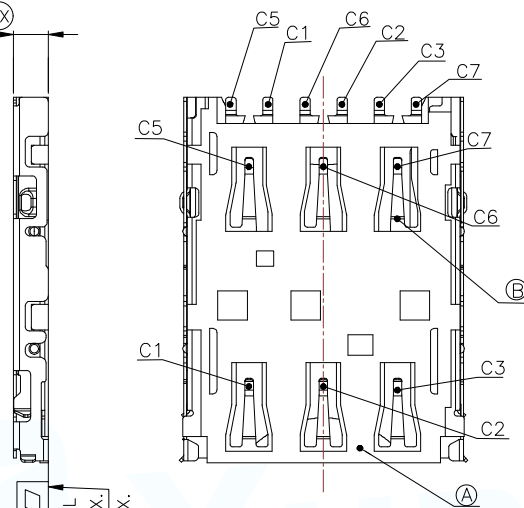
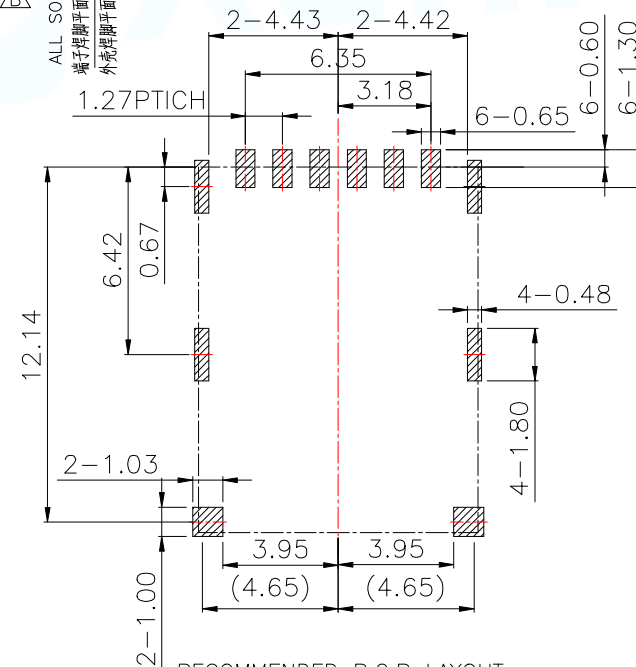




NANO SIM CARD PAD



ALL SOLDER-TAIL
端子焊脚平面度0.06MAX.
外壳焊脚平面度0.08MAX.



RECOMMENDED P.C.B LAYOUT
TOLERANCE(TOP VIEW) ±0.05mm

SPECIFICATIONS:

1.ELECTRICAL CHARACTERISTICS:

1-1.CURRENT RATING:1A

1-2.DIELECTRIC WITHSTANDING VOLTAGE:500V
R.M.S MIN;

1-3.INSULATION RESISTANCE:500MΩMIN.

1-4.CONTACT RESISTANCE:100mΩMAX.(INITIAL)

2.LIFE TEST: 1500 CYCLES.

C	SHELL	1	STAINLESS STEEL,0.10T	NICKEL PLATING OVER ALL
B	CONTACT	1	COPPER ALLOY,0.10T	GOLD FLASH ON CONTACT AREA AND SOLDER AREA 50u" MIN NICKEL UNDER-PLATED.
A	HOUSING	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES		 TITLE: NANO SIM H1.20		
DECIMALS:	ANGLES:	PAR	SMN-335-ARP6	
.X:±0.20	X":±2°	DWN		
.XX:±0.10	.X":±1°	CHKD		
.XXX:±0.05	.XX":±0.5°	APVD		
CUSTOMER COPY		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A